# LNJ318C8TRA

Surface Mounting Chip LED

Dome-Lens Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	60	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

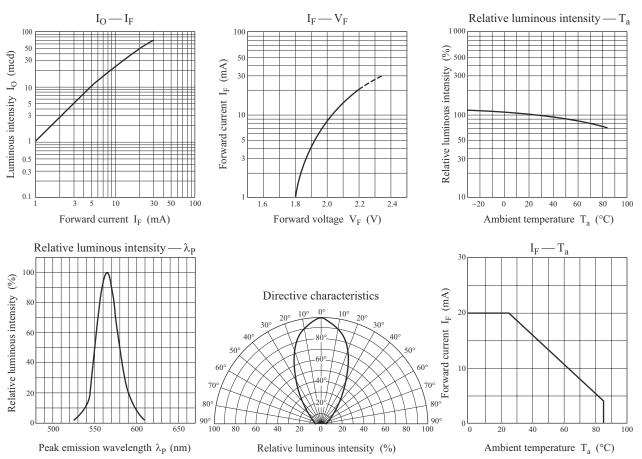
Lighting Color

Note) \*: The condition of IFP is duty 10%, Pulse width 1 msec.

#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I <sub>O</sub>	$I_{\rm F} = 10  {\rm mA}$	10	25		mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$			10	μΑ
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 10 \ {\rm mA}$		2.03	2.60	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		30		nm

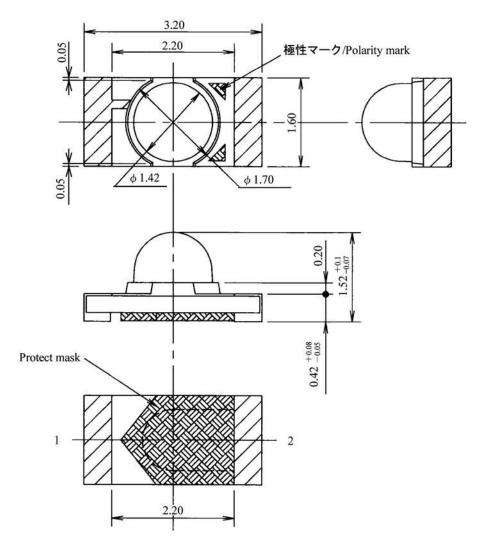
Note) \*: Measurement tolerance: ±20%



Yellow Green

Package (Unit: mm)

### KLTLTN2K1800



• Pin name

1: Anode

2: Cathode

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